What is claimed is:

1. A laminate comprising the combination of:

a base laminate including resin impregnated fabric sheet material having a first planar surface, a second planar surface, the fabric sheet having an original thickness of from about 10 to about 30 microns; and

at least one copper foil sheet that is adhered to a planar surface of the fabric sheet material by a cured resin wherein the base laminate thickness is from about 1.0 to about 1.75 mils .

2. The laminate of claim 1 wherein a copper foil sheet is adhered to each of the fabric sheet material first and second surfaces.

3. The laminate of claim 1 wherein the laminate has an average minimum dielectric thickness of no less than about 0.75 mils and an average maximum dielectric thickness no greater than about 1.5 mils.

4. The laminate of claim 1 wherein the laminate has an average minimum dielectric thickness of no less than about 0.8 mils and an average maximum dielectric thickness no greater than about 1.2 mils.

5. The laminate of claim 1 having a base laminate thickness of from about 1.3 to about 1.6 mils.

6. The laminate of claim 1 wherein the copper foil has a thickness of from about 15 to about 40 microns.

7. The laminate of claim 1 wherein the copper foil has a thickness of from about 15 to about 25 microns.

8. The laminate of claim 1 wherein the base laminate thickness differs by no more than 20% when measured at the center and each of four corners of a 18 inch by 24 inch rectangular laminate sheet.

9. The laminate of claim 1 wherein the resin includes no fillers.

10. The laminate of claim 9 wherein the resin includes a flow control agent.

11. The laminate of claim 10 wherein the flow control agent is a phenoxy resin that is present in the resin in an amount ranging from more than 0 wt.% to about 2 wt.% on a dry resin basis.

12. The laminate of claim 1 wherein the fabric layer is a woven glass fabric.

13. The laminate of claim 12 wherein the woven glass fabric has no more than 2 glass filaments stacked over and under wherein the glass filaments have a diameter of from about 3 microns to about 5 microns.

14. The laminate of claim 13 wherein the woven glass fabric has a filament diameter of about 4 microns.

15. The laminate of claim 1 wherein the fabric sheet has a thickness of from

about 10 to about 15 mils.

16. A laminate comprising the combination of:

a base laminate including a resin impregnated woven glass fabric having a first planar surface, a second planar; and

a copper foil sheet adhered to each of the first and second base laminate planar surfaces by the cured resin wherein the laminate has an average minimum dielectric thickness of no less than about .0.8 mils and an average maximum dielectric thickness of no greater than about 1.2 mils wherein the woven glass fabric has no more than 2 glass filaments stacked over and under.

17. The laminate of claim 16 wherein the resin T_g is from 180-200 °C.

18. A method for manufacturing an ultrathin laminate material comprising the steps of:

placing a first copper foil sheet having into contact with a first planar surface of a fabric sheet having a thickness of from 10 to about 30 microns wherein the fabric sheet is impregnated with a resin or a layer of resin lies between the first copper foil sheet and the fabric sheet first planar surface or both; and

applying pressure and heat to the stacked material for a time sufficient to essentially fully cure the resin to form a laminate sheet having a base laminate thickness of from about 1.0 to about 1.75 mils.

19. The method of claim 18 wherein a second copper sheet is placed into contact with a second planar surface of the fabric sheet before applying pressure

and heat to the stacked material wherein the fabric sheet is impregnated with a resin or a layer of resin lies between the second copper foil sheet and the fabric sheet second planar surface or both.

20. The method of claim 18 wherein a the copper foil includes a b-staged resin layer wherein the b-staged resin has a gel-time of 40-50 seconds and a viscosity of 15-25 Pascal seconds.

21. The method of claim 18 wherein the method is a continuous method.

22. The method of claim 18 wherein the laminate has an average minimum dielectric thickness of no less than about .080 mils and an average maximum dielectric thickness of no greater than about 1.2 mils.

23. The method of claim 18 wherein the fabric sheet is a woven glass fabric sheet.

24. The method of claim 18wherein the fabric sheet is impregnated with a resin before the resin impregnated fabric sheet is placed into contact with a first copper foil sheet and a second copper foil sheet.

25. The method of claim 18 wherein the first copper foil sheet includes a b-staged resin layer having a thickness of from about 10 to 25 microns.

26. The method of claim 18 wherein the fabric sheet is pre-wetted before

impregnating the fabric sheet with a resin.

27. The method of claim 18 wherein the fabric sheet is pre-wetted before placing a resin layer of a resin coated copper foil into contact with a planar surface of the fabric sheet.

28. A method for manufacturing an ultrathin laminate material comprising the steps of:

placing a first copper foil sheet having into contact with a first planar surface of a woven glass fabric sheet having a thickness of from 10 to about 30 microns wherein the fabric sheet is impregnated with a resin or a layer of resin lies between the first copper foil sheet and the fabric sheet first planar surface or both; and

applying pressure and heat to the stacked material for a time sufficient to essentially fully cure the resin to form a laminate sheet having an average minimum dielectric thickness of no less than about ..80 mils and an average maximum dielectric thickness of no greater than about 1.2 mils.

Claims:

1. An invention not claimed in any divisional application.